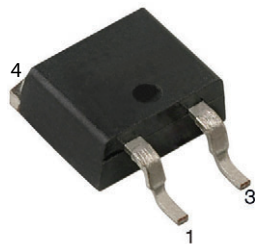
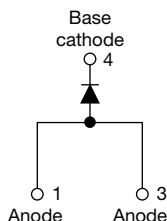


High Voltage Surface-Mount Input Rectifier Diode, 30 A



D²PAK 2L (TO-263AB 2L)



FEATURES

- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- 175 °C maximum operating junction temperature
- Glass passivated pellet chip junction
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Flexible solution for reliable AC power rectification
- High surge, low V_F rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	30 A
V_R	1200 V
V_F at I_F	1.20 V
I_{FSM}	255 A
T_J max.	175 °C
Package	D ² PAK 2L (TO-263AB 2L)
Circuit configuration	Single

APPLICATIONS

- Input rectification
- On-board and off-board EV / HEV battery chargers

DESCRIPTION

The VS-25ETS12SLHM3 rectifier High Voltage Series has been optimized for very low forward voltage drop, with moderate leakage.

MECHANICAL DATA

Case: D²PAK 2L (TO-263AB 2L)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

OUTPUT CURRENT IN TYPICAL APPLICATIONS			
APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS
Capacitive input filter $T_A = 55$ °C, $T_J = 125$ °C common heatsink of 1 °C/W	20	23	A

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	30	A
V_{RRM}		1200	V
I_{FSM}		255	A
V_F	10 A, $T_J = 25$ °C	1.0	V
T_J		-40 to +175	°C

VOLTAGE RATINGS			
PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 175 °C mA
VS-30ETS12S2LHM3	1200	1300	3

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 109\text{ }^{\circ}\text{C}$, 180° conduction half sine wave	30	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied, at $T_J = 175\text{ }^{\circ}\text{C}$	215	
		10 ms sine pulse, no voltage reapplied, at $T_J = 175\text{ }^{\circ}\text{C}$	255	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied, at $T_J = 175\text{ }^{\circ}\text{C}$	231	A^2s
		10 ms sine pulse, no voltage reapplied, at $T_J = 175\text{ }^{\circ}\text{C}$	326	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1\text{ ms to }10\text{ ms}$, no voltage reapplied, at $T_J = 175\text{ }^{\circ}\text{C}$	3260	$\text{A}^2\sqrt{\text{s}}$

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop	V_{FM}	30 A, $T_J = 25\text{ }^{\circ}\text{C}$	1.20	V
Forward slope resistance	r_t	$T_J = 175\text{ }^{\circ}\text{C}$	12	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$		0.83	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$	1.0	
		$T_J = 175\text{ }^{\circ}\text{C}$	3.0	

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +175	$^{\circ}\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	0.9	$^{\circ}\text{C/W}$
Maximum thermal resistance, junction to ambient	$R_{thJA}^{(1)}$	For D ² PAK version	62	
Typical thermal resistance, case to heatsink	R_{thCS}	Mounting surface, smooth, and greased	0.5	
Approximate weight			2	g
			0.07	oz.
Marking device		Case style: D ² PAK 2L (TO-263AB 2L)	30ETS12SH	

Note

(1) When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 $^{\circ}\text{C/W}$

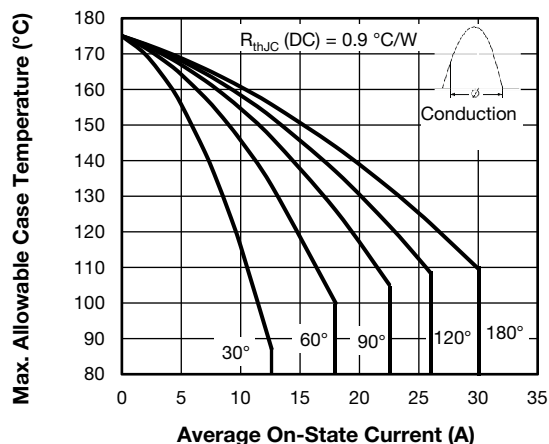


Fig. 1 - Current Rating Characteristics

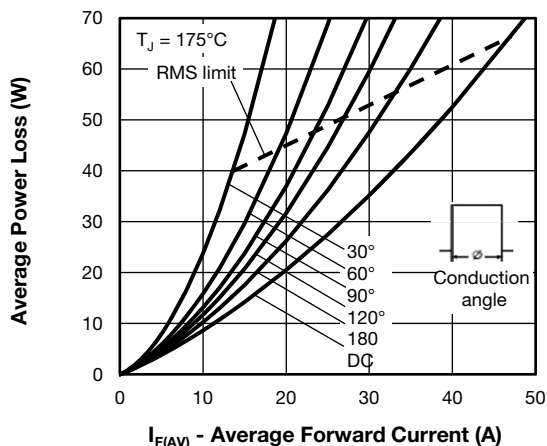


Fig. 4 - Forward Power Loss Characteristics

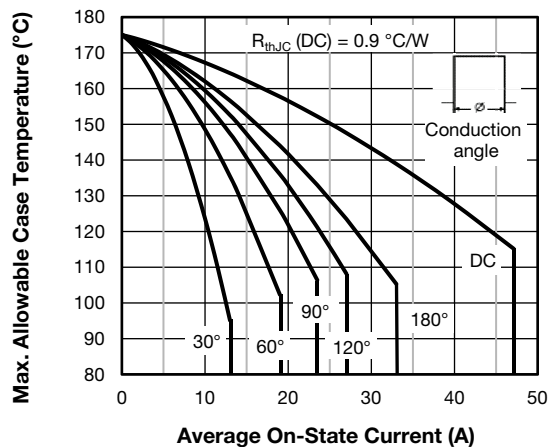


Fig. 2 - Current Rating Characteristics

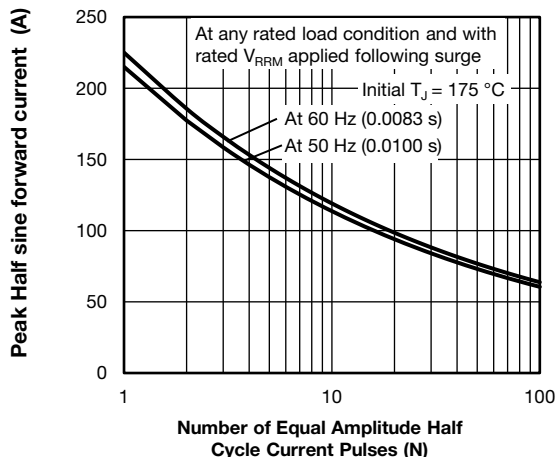


Fig. 5 - Maximum Non-Repetitive Surge Current

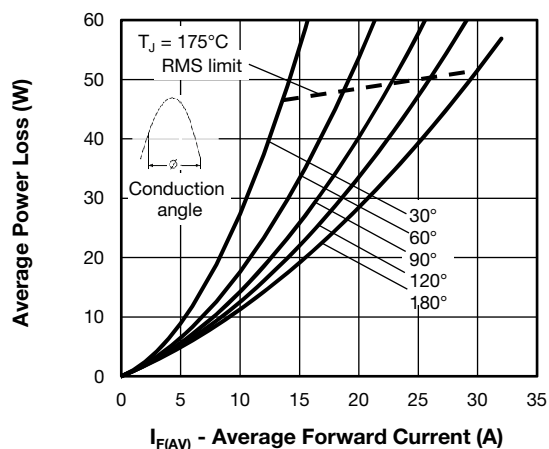


Fig. 3 - Forward Power Loss Characteristics

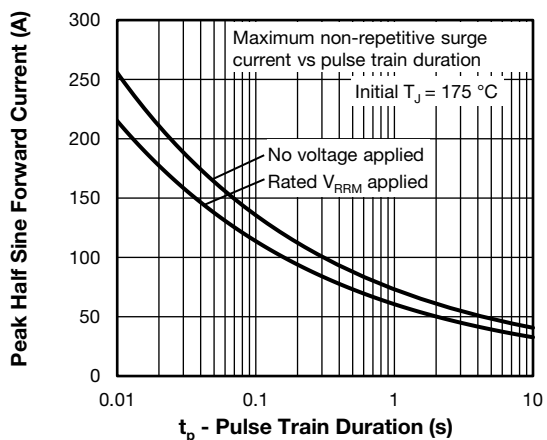


Fig. 6 - Maximum Non-Repetitive Surge Current

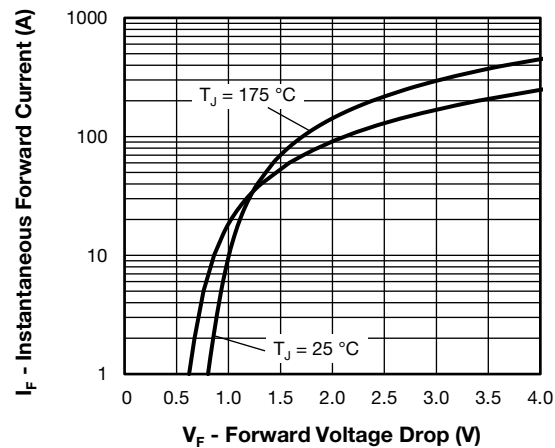
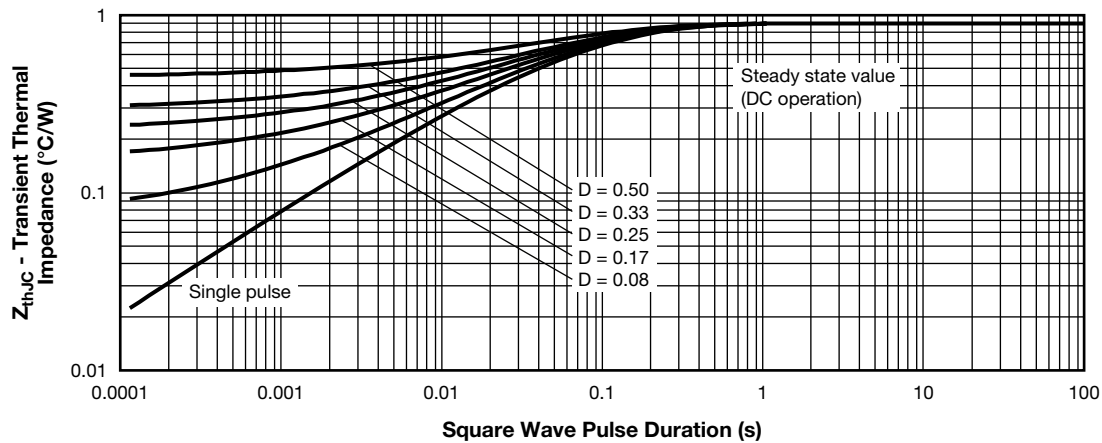


Fig. 7 - Forward Voltage Drop Characteristics


Fig. 8 - Thermal Impedance Z_{thJC} Characteristics

**ORDERING INFORMATION TABLE**

Device code	VS-	30	E	T	S	12	S	2	L	H	M3
	①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩	⑪

- 1** - Vishay Semiconductors product
- 2** - Current rating (30 = 30 A)
- 3** - Circuit configuration
E = single diode
- 4** - Package:
T = D²PAK
- 5** - Type of silicon:
S = standard recovery rectifier
- 6** - Voltage code x 100 = V_{RRM} ——— **12 = 1200 V**
- 7** - S = surface mountable
- 8** - 2 = true 2 pin D²PAK
- 9** - L = tape and reel (left oriented), for different orientation, contact factory
- 10** - H = AEC-Q101 qualified
- 11** - Environmental digit:
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-30ETS12S2LHM3	800	800	13" diameter reel

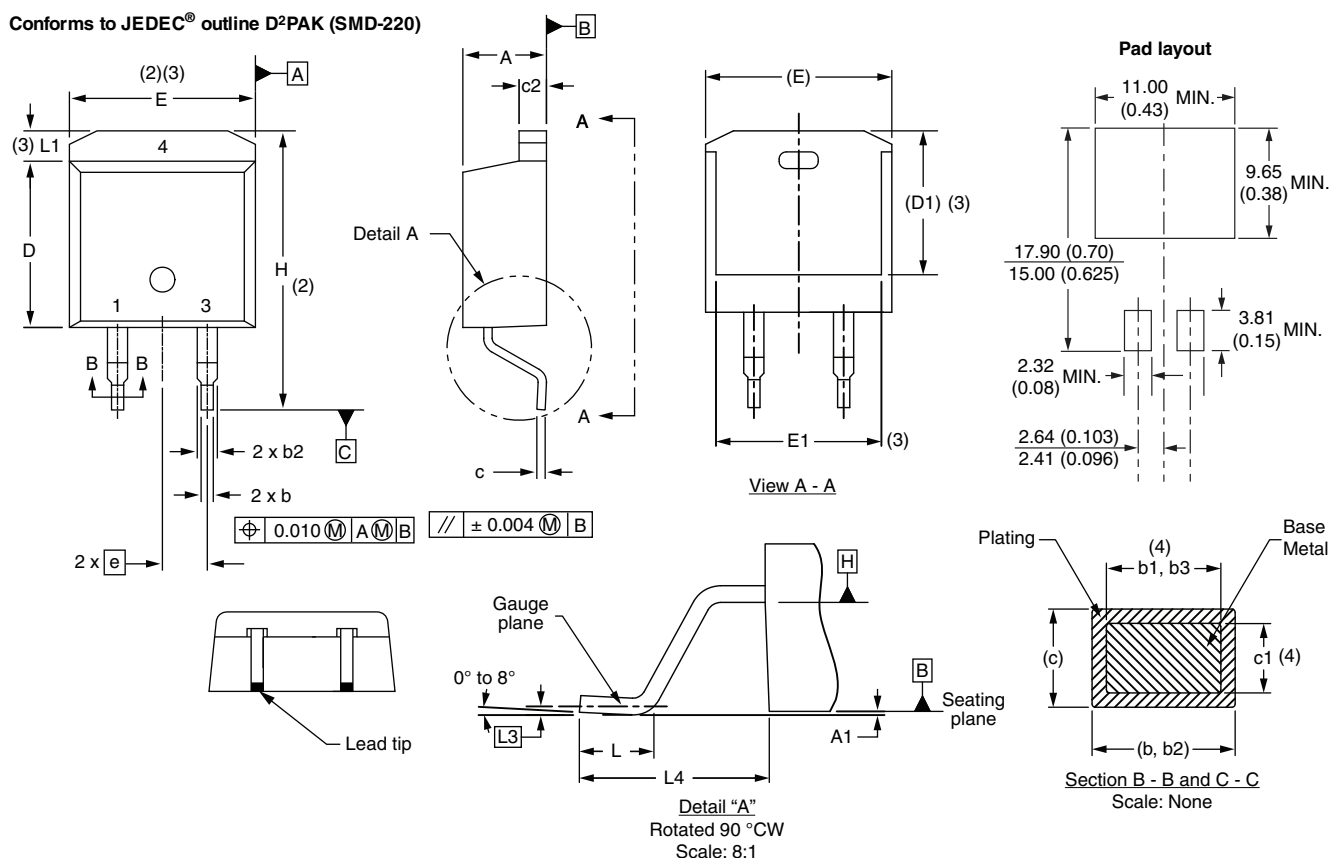
LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?96683
Part marking information	www.vishay.com/doc?96693
Packaging information	www.vishay.com/doc?95032

D²PAK 2L (TO-263AB 2L)

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB



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